

## Single N-Channel Enhancement Mode MOSFET

$V_{DS}=75V$ ,  $I_D=80A$ ,  $R_{DS(ON)}=7m\Omega$

### DESCRIPTION

The OR8090A is N-Channel logic enhancement mode power field effect transistors designed for high current switching applications.

Rugged  $E_{AS}$  capability and ultra low  $R_{DS(ON)}$  is suitable for PWM, load switching especially for E-Bike controller applications.

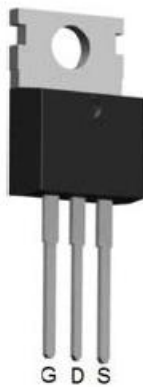
### FEATURE

- ◆  $75V/80A$ :  $R_{DS(ON)}=7m\Omega@V_{GS}=10V$
- ◆ Super high density cell design for extremely low  $R_{DS(ON)}$
- ◆ Special designed for E-bike controller
- ◆ Full ROHS compliance
- ◆ TO-220 package design

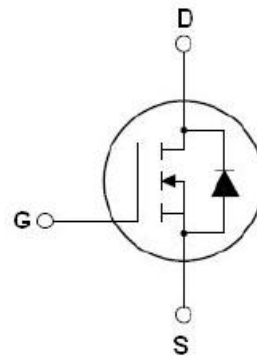
### APPLICATIONS

- ◆ E-bike controller applications
- ◆ Hard switched and high frequency circuits
- ◆ Uninterruptible power supply

### PIN CONFIGURATION



To-220 Top View



Schematic Diagram

## ■ ABSOLUTE MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ Unless otherwise noted)

Symbol	Parameter	Typical	Unit
$V_{DSS}$	Drain-Source Voltage	75	V
$V_{GSS}$	Gate-Source Voltage	+20	V
$I_D$	Continuous Drain Current( $T_J=150^{\circ}\text{C}$ )	$V_{GS}=-10\text{V}$ 80	A
$I_{DM}$	Pulsed Drain Current	320	A
$T_J$	Operation Junction Temperature	-55~175	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-55~175	$^{\circ}\text{C}$
$P_D$	Power Dissipation( $T_C=25^{\circ}\text{C}$ )	103	W
$E_{AS}$	Single Pulse Avalanche Energy ( $T_J=25^{\circ}\text{C}, V_{DD}=40\text{V}, V_{GS}=10\text{V}, R_G=25\Omega$ )	110	mJ
$R_{\theta JC}$	Thermal Resistance-Junction to Ambient	1.46	$^{\circ}\text{C}/\text{W}$

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## ■ ELECTRICAL CHARACTERISTICS ( $T_A=25^{\circ}\text{C}$ Unless otherwise noted)

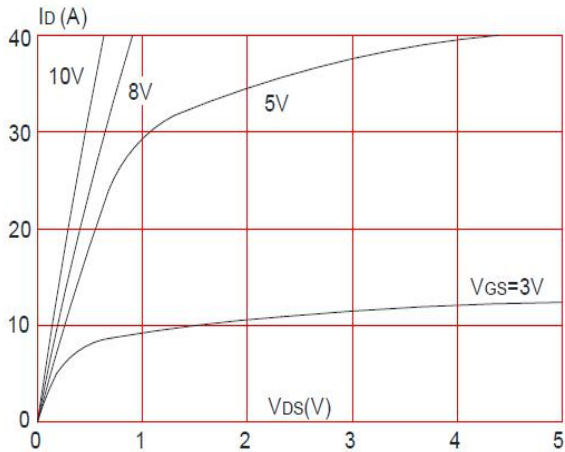
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_{DS}=250\mu\text{A}$	68	75	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$	2	3	4	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	+100	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=58\text{V}, V_{GS}=0\text{V}$ $T_C=25^{\circ}\text{C}$	-	-	1	$\mu\text{A}$
		$V_{DS}=68\text{V}, V_{GS}=0\text{V}$ $T_C=125^{\circ}\text{C}$	-	-	10	$\mu\text{A}$
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_{DS}=30\text{A}$	-	7.0	9	$\text{m}\Omega$
Source-Drain Diode						
$I_S$	Diode Forward Current (Max.)		-	80	-	A
$V_{SD}$	Diode Forward Voltage	$I_S=40\text{A}, V_{GS}=0\text{V}$	-	-	1.2	V
Dynamic Parameters						
$Q_g$	Total Gate Charge	$V_{DS}=30\text{V}, V_{GS}=10\text{V}$ $I_D=30\text{A}$	-	35	-	nC
$Q_{gs}$	Gate-Source Charge		-	10	-	
$Q_{gd}$	Gate-Drain Charge		-	9	-	
$C_{iss}$	Input Capacitance	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $F=1\text{MHz}$	-	4000	-	pF
$C_{oss}$	Output Capacitance		-	267	-	
$C_{rss}$	Reverse Transfer Capacitance		-	250	-	
$t_{d(on)}$	Turn-On Time	$V_{DS}=30\text{V}, I_D=30\text{A}$ $V_{GS}=10\text{V}, R_G=3\Omega$	-	15	-	nS
$t_r$			-	90	-	
$t_{d(off)}$	Turn-Off Time		-	45	-	
$t_f$			-	30	-	

Note: 1. Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ ;

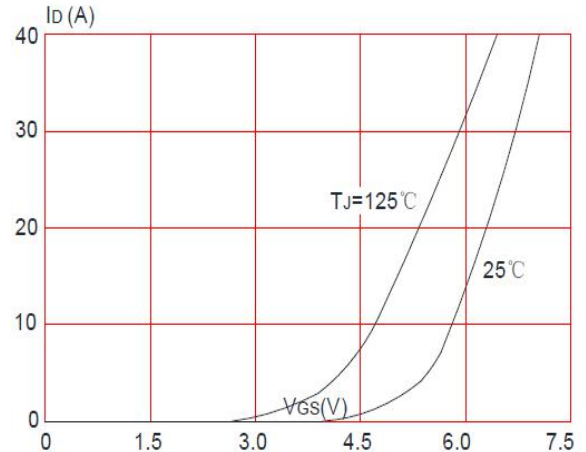
2. Static parameters are based on package level with recommended wire-bonding

**TYPICAL CHARACTERISTICS** ( $T_A=25^{\circ}C$  Unless otherwise noted)

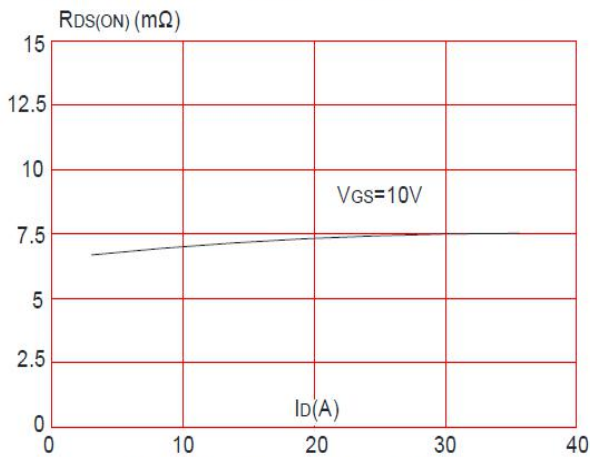
**Figure 1: Output Characteristics**



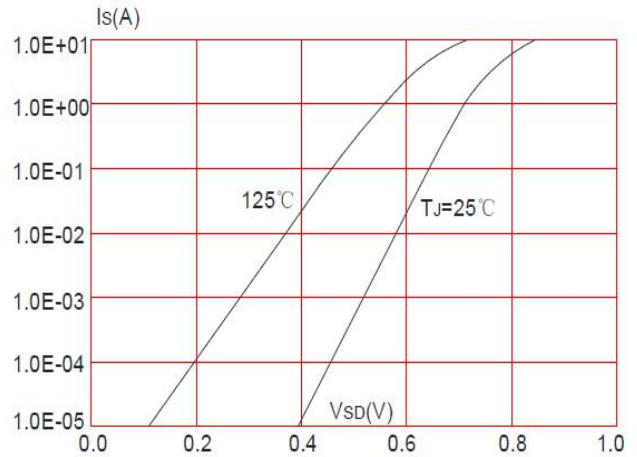
**Figure 2: Typical Transfer Characteristics**



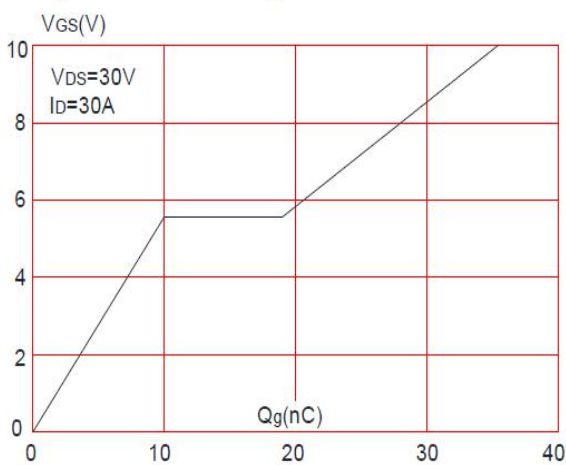
**Figure 3: On-resistance vs. Drain Current**



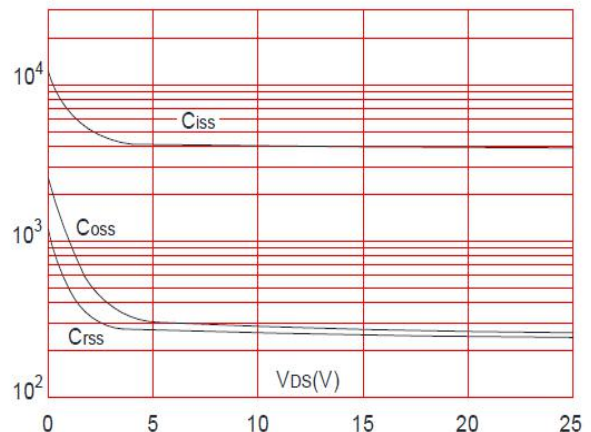
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

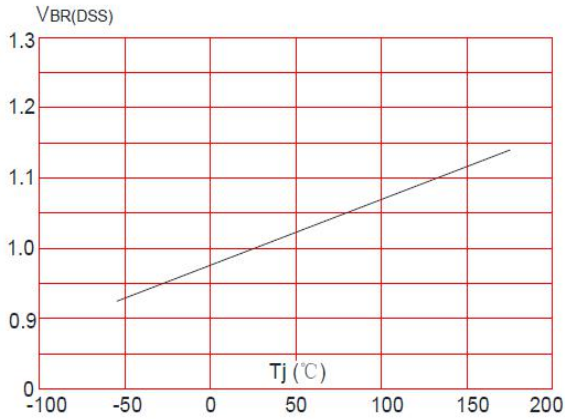


**Figure 6: Capacitance Characteristics**

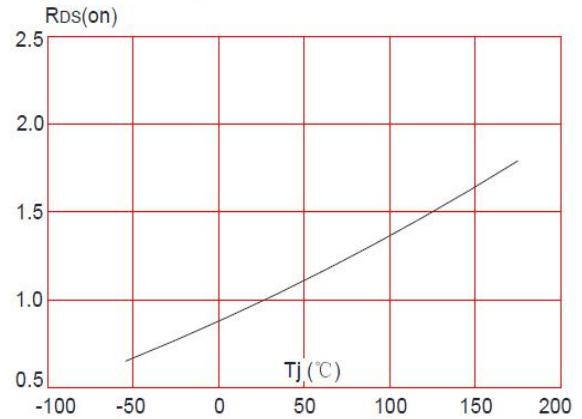


## TYPICAL CHARACTERISTICS ( $T_A=25^{\circ}\text{C}$ Unless otherwise noted) (Continue)

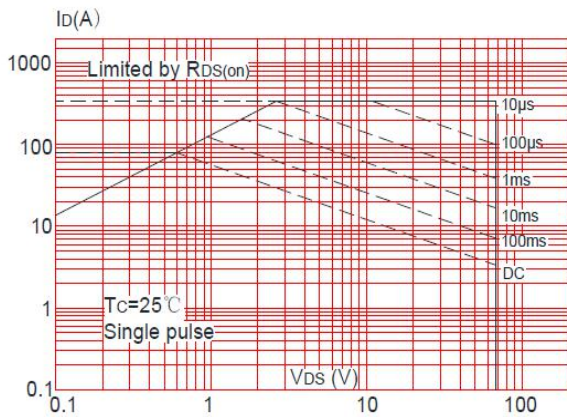
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



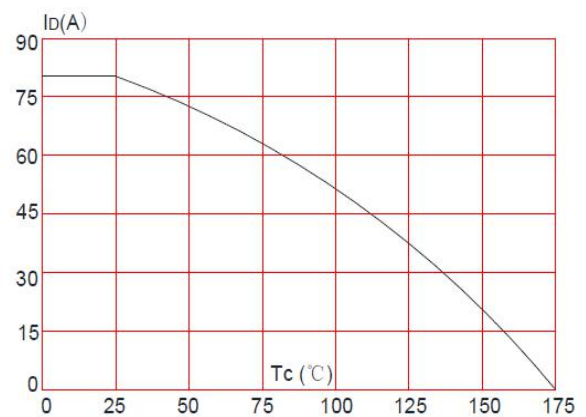
**Figure 8:** Normalized on Resistance vs. Junction Temperature



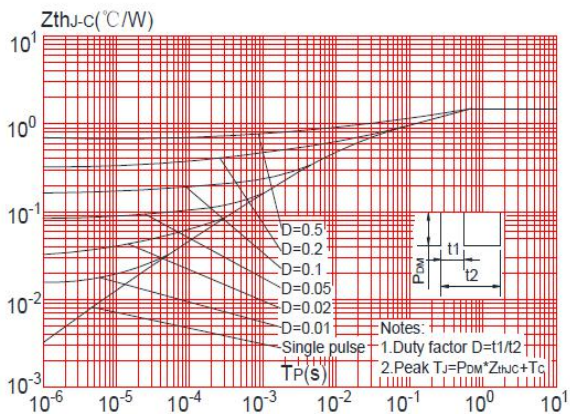
**Figure 9:** Maximum Safe Operating Area



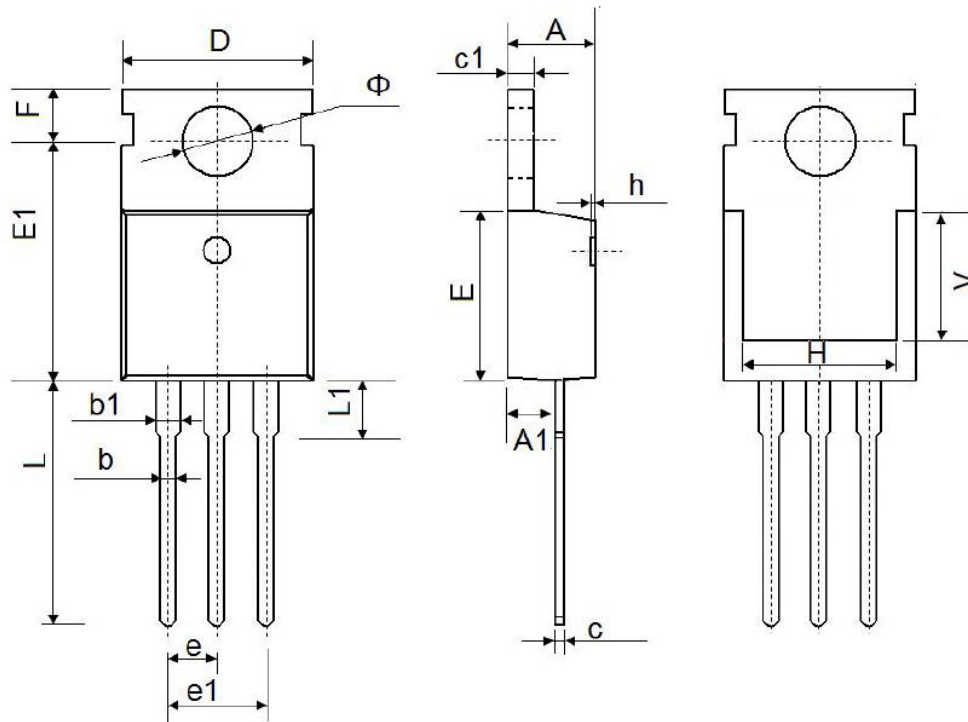
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



## T0-220 PACKAGE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150